URL for Additional Information

PART INFORMATION

Mfg Item Number

Mfg Item Name

TSSOP 16 4.4*5*1.0P0.65

SUPPLIER Company Name Freescale Semiconductor Inc Company Unique ID 14-141-7928 Response Date 2015-06-08 Response Document ID 6117K11060D043A1.6 Contact Name Freescale Semiconductor Inc Contact Title Product Technical Support **Contact Phone** 1-800-521-6274 Contact Email support@freescale.com **Authorized Representative** Daniel Binyon Representative Title **EPP Customer Response** Representative Phone 512-895-3406 Representative Email eppanlst@freescale.com

DECLARATION

EU RoHS
Pb Free
HalogenFree
Plating Indicator
EU RoHS Exemption(s)

www.freescale.com

MANUFACTURING Mfg Item Number MC9RS08KB8CTG Mfg Item Name TSSOP 16 4.4*5*1.0P0.65 Version ALL Weight 0.062200 UoM Unit Volume EACH J-STD-020 MSL Rating 3 Peak Processing Temperature 260 C Max Time at Peak Temperature 40 seconds Number of Processing Cycles 3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Co
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight
Exemptions	6(b): Lead as an alloying element in aluminium containing up to 0.4% lead by weight
	6(c): Copper alloy containing up to 4% lead by weight
	7(a): Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
	7(b): Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications
	7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
	7(c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
	7(c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC
	7(c)-IV: Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors
	15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Lead Frame Plating	0.0022						g				
Lead Frame Plating		Lead/Lead Compounds	Lead	7439-92-1		0.00000044	g	200	0.02	7	0.0007
Lead Frame Plating		Metals	Tin, metal	7440-31-5		0.00219956	g	999800	99.98	35362	3.5362
Copper Lead Frame	0.0279						g				
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.02624166	g	940562	94.0562	421903	42.1903
Copper Lead Frame		Solvents, additives, and other materials	Silicon	7440-21-3		0.00020228	g	7250	0.725	3252	0.3252
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.00003488	g	1250	0.125	560	0.056
Copper Lead Frame		Lead/Lead Compounds	Lead	7439-92-1		0.00000873	g	313	0.0313	140	0.014
Copper Lead Frame		Metals	Magnesium, metal	7439-95-4		0.00004883	g	1750	0.175	785	0.0785
Copper Lead Frame		Metals	Manganese, metal	7439-96-5		0.00001744	g	625	0.0625	280	0.028
Copper Lead Frame		Nickel (external applications only)	Nickel	7440-02-0		0.0008928	g	32000	3.2	14353	1.4353
Copper Lead Frame		Metals	Silver, metal	7440-22-4		0.000279	g	10000	1	4485	0.4485
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.00017438	g	6250	0.625	2803	0.2803
Silicon Semiconductor Die	0.0032						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000064	g	20000	2	1028	0.1028
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.003136	g	980000	98	50418	5.0418
Epoxy Die Attach	0.0009						g				
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.00072486	g	805406	80.5406	11653	1.1653
Epoxy Die Attach		Solvents, additives, and other materials	Proprietary Material-Other miscellaneous substances.	-		0.00002919	g	32432	3.2432	469	0.0469
Epoxy Die Attach		Plastics/polymers	Proprietary Material-Other Non-halogenated Epoxy resin	s -		0.00014595	g	162162	16.2162	2346	0.2346
Bonding Wire, Copper	0.0004						g				
Bonding Wire, Copper		Metals	Copper, metal	7440-50-8		0.000388	g	970000	97	6237	0.6237
Bonding Wire, Copper		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000012	g	30000	3	192	0.0192
Die Encapsulant	0.0276						g				
Die Encapsulant		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.0000552	g	2000	0.2	887	0.0887
Die Encapsulant		Plastics/polymers	Proprietary Material-Other phenolic resins	-		0.001242	g	45000	4.5	19967	1.9967
Die Encapsulant		Glass	Silica, vitreous	60676-86-0		0.0250608	g	908000	90.8	402906	40.2906
Die Encapsulant		Plastics/polymers	Proprietary Material-Other Non-halogenated Epoxy resin	s -		0.001242	g	45000	4.5	19967	1.9967

LINKS

MCD LINK

http://www.freescale.com Freescale website

GENERAL ENVIRONMENTAL COMPLIANCE LINKS

http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf RoHS signed letter China RoHS http://www.freescale.com/chinarohs

REACH signed letter $http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf$

ELV signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf **Conflict Minerals statement** $http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf$

FREESCALE ENVIRONMENTAL INFORMATION

EPP website http://www.freescale.com/epp

FAQ http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ

Technical Service Request

LINKS TO BLANK IPC1752 FORMS

https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod

Blank IPC1752 v1.1 Form http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MC9RS08KB8CTG_IPC1752_v11.xml

http://www.freescale.com/mcds/MC9RS08KB8CTG_IPC1752A.xml